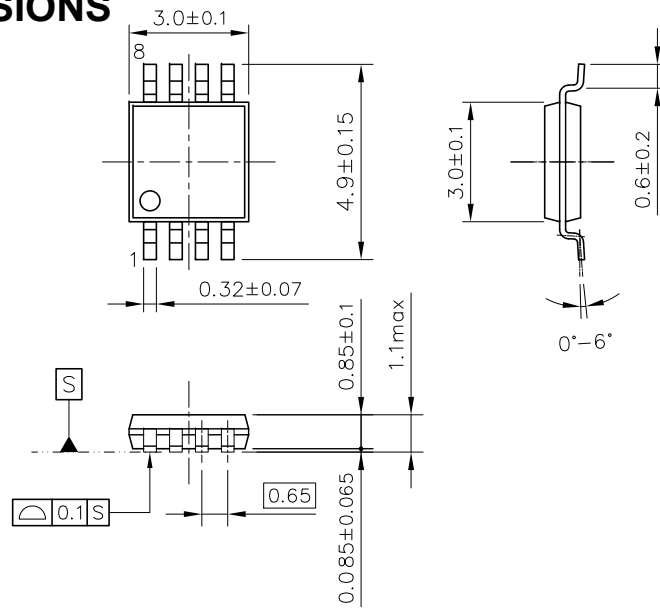


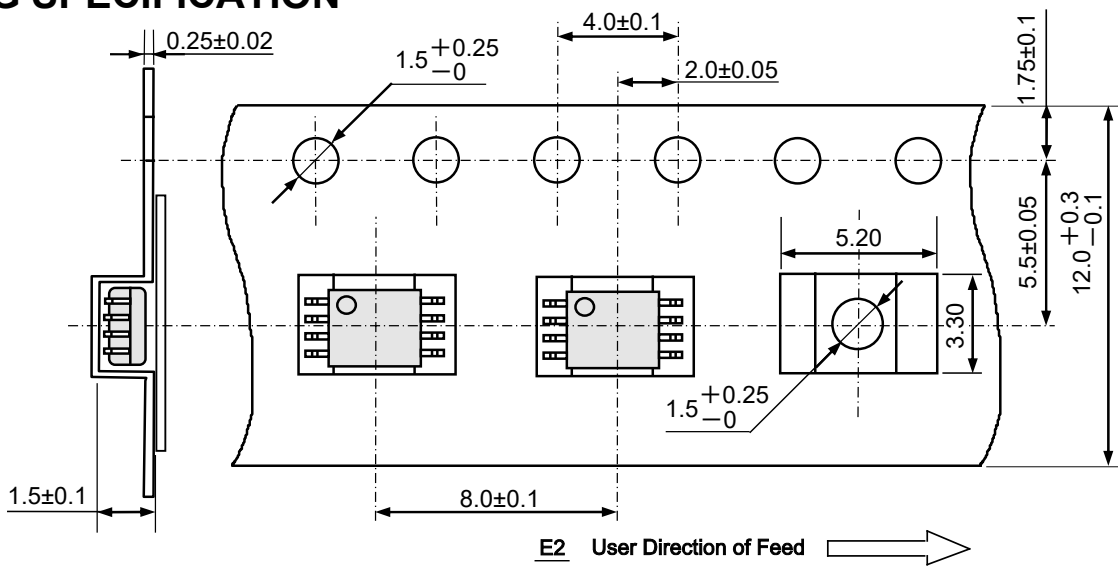
• MSOP-8

Unit: mm

PACKAGE DIMENSIONS

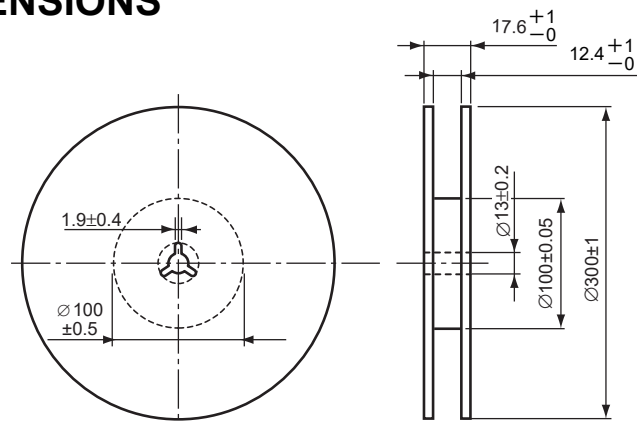


TAPING SPECIFICATION



TAPING REEL DIMENSIONS

1 reel = 3,000 pcs



## POWER DISSIPATION (MSOP-8)

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

### Measurement Conditions

Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square
Through-holes	φ 0.3 mm × 32 pcs

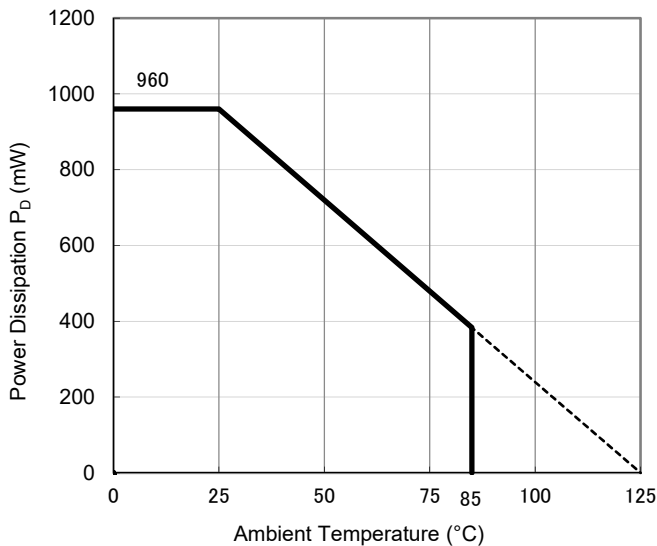
### Measurement Result

(Ta = 25°C, Tjmax = 125°C)

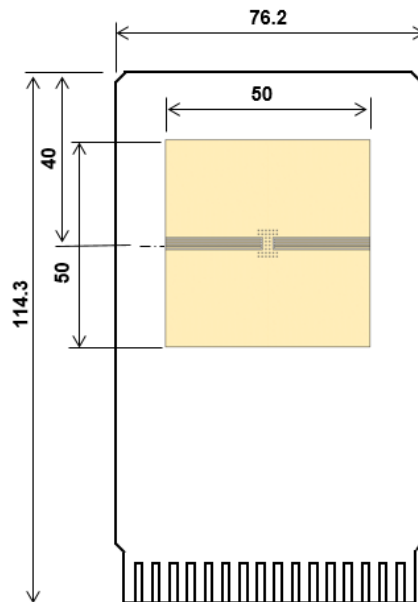
Item	Measurement Result
Power Dissipation	960 mW
Thermal Resistance ( $\theta_{ja}$ )	$\theta_{ja} = 104^{\circ}\text{C/W}$
Thermal Characterization Parameter ( $\psi_{jt}$ )	$\psi_{jt} = 31^{\circ}\text{C/W}$

$\theta_{ja}$ : Junction-to-Ambient Thermal Resistance

$\psi_{jt}$ : Junction-to-Top Thermal Characterization Parameter



Power Dissipation vs. Ambient Temperature



Measurement Board Pattern

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

**Measurement Conditions**

Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square
Through-holes	φ 0.3 mm × 32 pcs

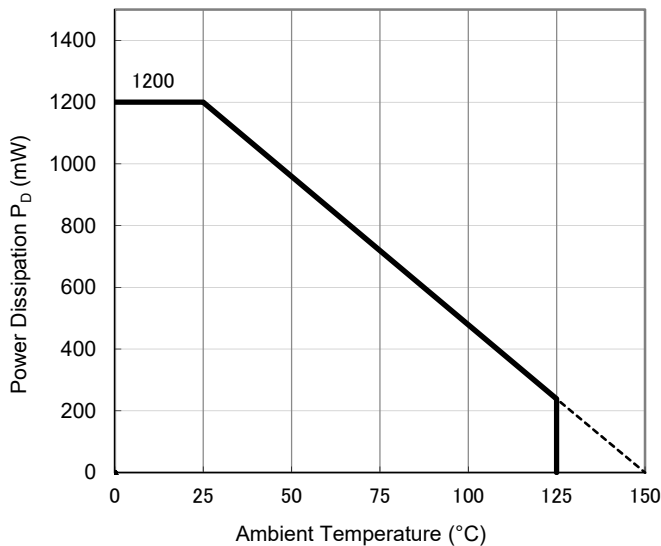
**Measurement Result**

(Ta = 25°C, Tjmax = 150°C)

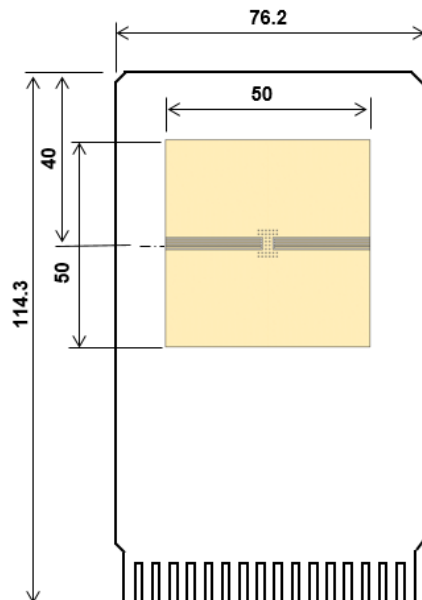
Item	Measurement Result
Power Dissipation	1200 mW
Thermal Resistance ( $\theta_{ja}$ )	$\theta_{ja} = 104^{\circ}\text{C/W}$
Thermal Characterization Parameter ( $\psi_{jt}$ )	$\psi_{jt} = 31^{\circ}\text{C/W}$

$\theta_{ja}$ : Junction-to-Ambient Thermal Resistance

$\psi_{jt}$ : Junction-to-Top Thermal Characterization Parameter



**Power Dissipation vs. Ambient Temperature**



**Measurement Board Pattern**

RECOMMENDED LAND PATTERN

